

IS61LV25616

256K x 16 HIGH SPEED ASYNCHRONOUS CMOS STATIC RAM WITH 3.3V SUPPLY

FEATURES

- High-speed access time: 8, 10, 12, and 15 ns
- CMOS low power operation
- TTL compatible interface levels
- Single 3.3V ± 10% power supply
- Fully static operation: no clock or refresh required
- Three state outputs
- Data control for upper and lower bytes
- Industrial temperature available

DESCRIPTION

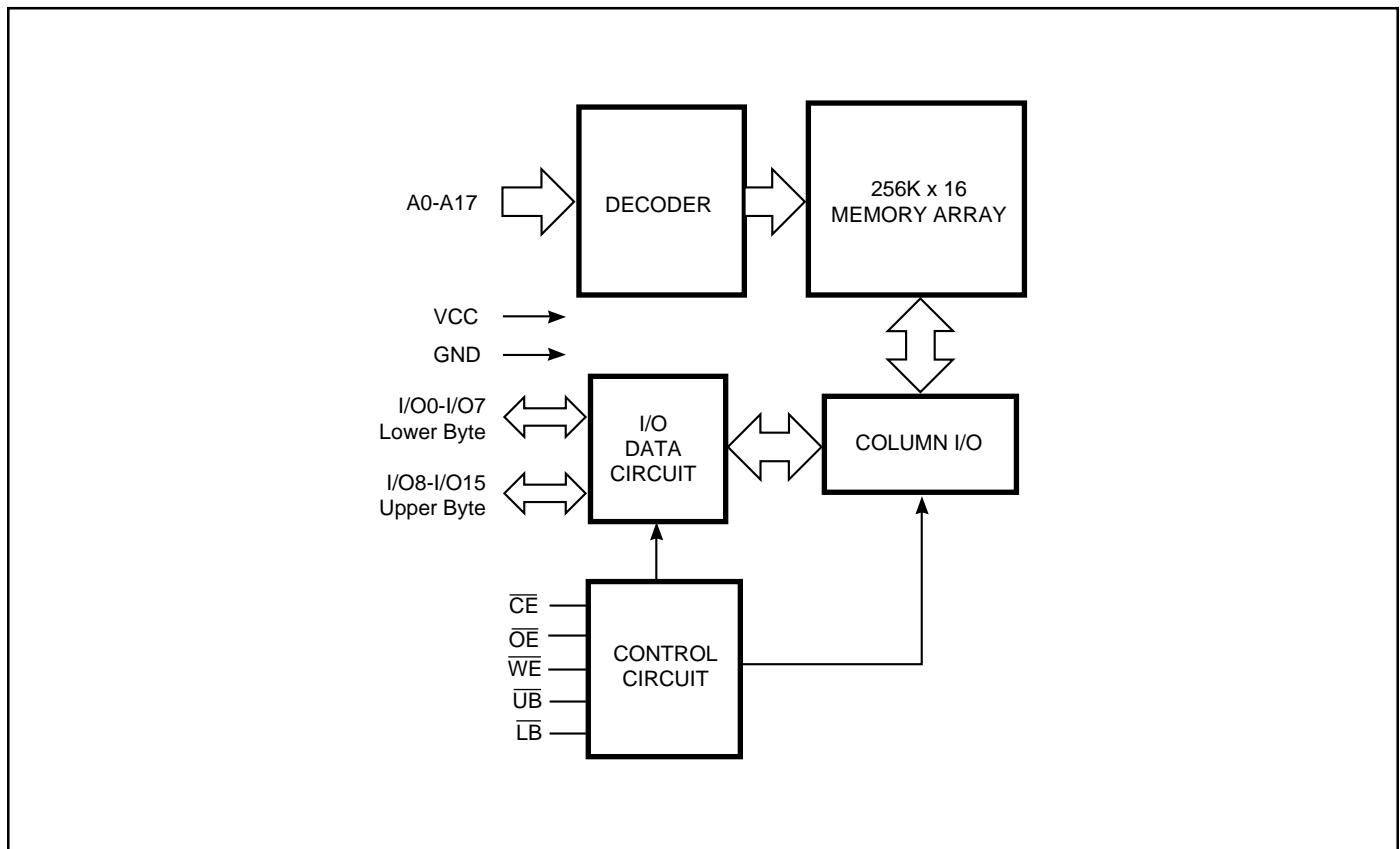
The *ICSI* IS61LV25616 is a high-speed, 4,194,304-bit static RAM organized as 262,144 words by 16 bits. It is fabricated using *ICSI*'s high-performance CMOS technology. This highly reliable process coupled with innovative circuit design techniques, yields high-performance and low power consumption devices.

When \overline{CE} is HIGH (deselected), the device assumes a standby mode at which the power dissipation can be reduced down with CMOS input levels.

Easy memory expansion is provided by using Chip Enable and Output Enable inputs, \overline{CE} and \overline{OE} . The active LOW Write Enable (\overline{WE}) controls both writing and reading of the memory. A data byte allows Upper Byte (\overline{UB}) and Lower Byte (\overline{LB}) access.

The IS61LV25616 is packaged in the JEDEC standard 44-pin 400mil SOJ, 44 pin 400mil TSOP-2 and 48-pin 6*8 TF-BGA.

FUNCTIONAL BLOCK DIAGRAM



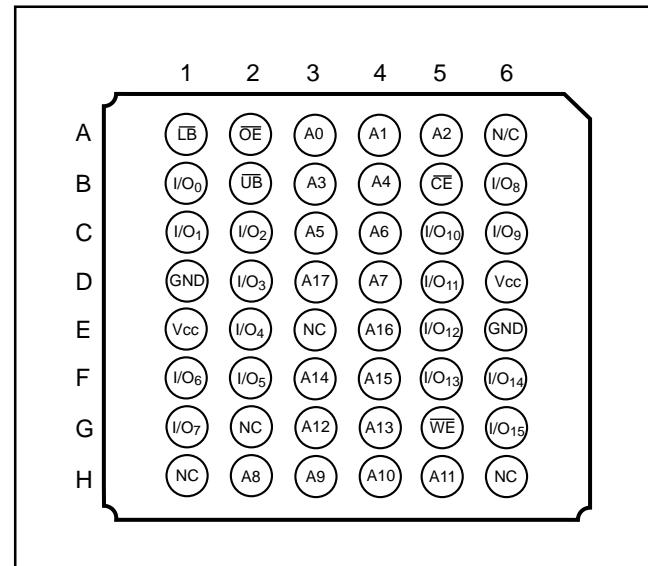
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PIN CONFIGURATIONS

44-Pin TSOP-2 and SOJ

A0	1	44	A17
A1	2	43	A16
A2	3	42	A15
A3	4	41	OE
A4	5	40	UB
CE	6	39	LB
I/O0	7	38	I/O15
I/O1	8	37	I/O14
I/O2	9	36	I/O13
I/O3	10	35	I/O12
Vcc	11	34	GND
GND	12	33	Vcc
I/O4	13	32	I/O11
I/O5	14	31	I/O10
I/O6	15	30	I/O9
I/O7	16	29	I/O8
WE	17	28	NC
A5	18	27	A14
A6	19	26	A13
A7	20	25	A12
A8	21	24	A11
A9	22	23	A10

48-Pin TF-BGA



PIN DESCRIPTIONS

A0-A17	Address Inputs
I/O0-I/O15	Data Inputs/Outputs
CE	Chip Enable Input
OE	Output Enable Input
WE	Write Enable Input

LB	Lower-byte Control (I/O0-I/O7)
UB	Upper-byte Control (I/O8-I/O15)
NC	No Connection
Vcc	Power
GND	Ground

TRUTH TABLE

Mode	WE	CE	OE	LB	UB	I/O PIN		
						I/O0-I/O7	I/O8-I/O15	Vcc Current
Not Selected	X	H	X	X	X	High-Z	High-Z	ISB1, ISB2
Output Disabled	H	L	H	X	X	High-Z	High-Z	Icc
Read	X	L	X	H	H	High-Z	High-Z	
	H	L	L	L	H	DOUT	High-Z	Icc
	H	L	L	L	L	High-Z	DOUT	
Write	L	L	X	L	H	DIN	High-Z	Icc
	L	L	X	H	L	High-Z	DIN	
	L	L	X	L	L	DIN	DIN	

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Parameter	Value	Unit
VTERM	Terminal Voltage with Respect to GND	-0.5 to Vcc+0.5	V
TBIAS	Temperature Under Bias	-45 to +90	°C
Vcc	Vcc Related to GND	-0.3 to +4.0	V
TSTG	Storage Temperature	-65 to +150	°C
PT	Power Dissipation	1.0	W

Note:

1. Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

OPERATING RANGE

Range	Ambient Temperature	Vcc
Commercial	0°C to +70°C	3.3V ± 10%
Industrial	-40°C to +85°C	3.3V ± 10%

DC ELECTRICAL CHARACTERISTICS (Over Operating Range)

Symbol	Parameter	Test Conditions	Min.	Max.	Unit
V _{OH}	Output HIGH Voltage	Vcc = Min., I _{OH} = -4.0 mA	2.4	—	V
V _{OL}	Output LOW Voltage	Vcc = Min., I _{OL} = 8.0 mA	—	0.4	V
V _{IH}	Input HIGH Voltage		2.0	Vcc + 0.3	V
V _{IL}	Input LOW Voltage ⁽¹⁾		-0.3	0.8	V
I _{LI}	Input Leakage	GND ≤ V _{IN} ≤ Vcc	Com. Ind.	-1 5	μA
I _{LO}	Output Leakage	GND ≤ V _{OUT} ≤ Vcc Outputs Disabled	Com. Ind.	-1 5	μA

Notes:

1. V_{IL} (min.) = -2.0V for pulse width less than 10 ns.
2. The Vcc operating range for 8 ns is 3.3V +10%, -5%.

POWER SUPPLY CHARACTERISTICS⁽¹⁾ (Over Operating Range)

Symbol	Parameter	Test Conditions	-8 ns		-10 ns		-12 ns		-15 ns		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
I _{CC}	Vcc Dynamic Operating Supply Current	Vcc = Max., I _{OUT} = 0 mA, f = f _{MAX}	Com. Ind.	- 350 360	— 320 330	— 290 300	— 260 270	— 290 300	— 260 270	— 260 270	mA
I _{S81}	TTL Standby Current (TTL Inputs)	Vcc = Max., V _{IN} = V _{IH} or V _{IL} , $\overline{CE} \geq V_{IH}$, f = 0	Com. Ind.	— 55 65	mA						
I _{S82}	CMOS Standby Current (CMOS Inputs)	Vcc = Max., $\overline{CE} \geq Vcc - 0.2V$, V _{IN} ≥ Vcc - 0.2V, or V _{IN} ≤ 0.2V, f = 0	Com. Ind.	— 10 15	mA						

Note:

1. At f = f_{MAX}, address and data inputs are cycling at the maximum frequency, f = 0 means no input lines change.

CAPACITANCE⁽¹⁾

Symbol	Parameter	Conditions	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 0V	6	pF
C _{OUT}	Input/Output Capacitance	V _{OUT} = 0V	8	pF

Note:

1. Tested initially and after any design or process changes that may affect these parameters.

READ CYCLE SWITCHING CHARACTERISTICS⁽¹⁾ (Over Operating Range)

Symbol	Parameter	-8		-10		-12		-15		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t _{RC}	Read Cycle Time	8	—	10	—	12	—	15	—	ns
t _{AA}	Address Access Time	—	8	—	10	—	12	—	15	ns
t _{OH} A	Output Hold Time	3	—	3	—	3	—	3	—	ns
t _{ACE}	CE Access Time	—	8	—	10	—	12	—	15	ns
t _{DOE}	OE Access Time	—	4	—	5	—	6	—	7	ns
t _{HZOE} ⁽²⁾	OE to High-Z Output	0	4	—	5	—	6	0	6	ns
t _{LZOE} ⁽²⁾	OE to Low-Z Output	0	—	0	—	0	—	0	—	ns
t _{HZCE} ⁽²⁾	CE to High-Z Output	0	4	0	5	0	6	0	6	ns
t _{LZCE} ⁽²⁾	CE to Low-Z Output	3	—	3	—	3	—	3	—	ns
t _{BA}	LB, UB Access Time	—	4	—	5	—	6	—	7	ns
t _{HZB}	LB, UB to High-Z Output	0	4	0	5	0	6	0	6	ns
t _{LZB}	LB, UB to Low-Z Output	0	—	0	—	0	—	0	—	ns

Notes:

- Test conditions assume signal transition times of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V and output loading specified in Figure 1a.
- Tested with the load in Figure 1b. Transition is measured ± 500 mV from steady-state voltage. Not 100% tested.
- Not 100% tested.

AC TEST CONDITIONS

Parameter	Unit
Input Pulse Level	0V to 3.0V
Input Rise and Fall Times	3 ns
Input and Output Timing and Reference Level	1.5V
Output Load	See Figures 1 and 2

Notes:

- The V_{CC} operating range for 8 ns is 3.3V +10%, -5%.

AC TEST LOADS

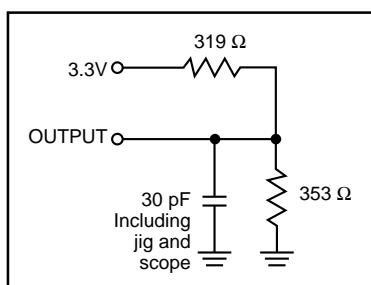


Figure 1

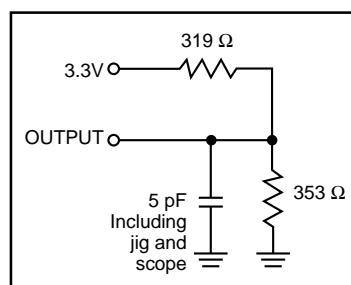
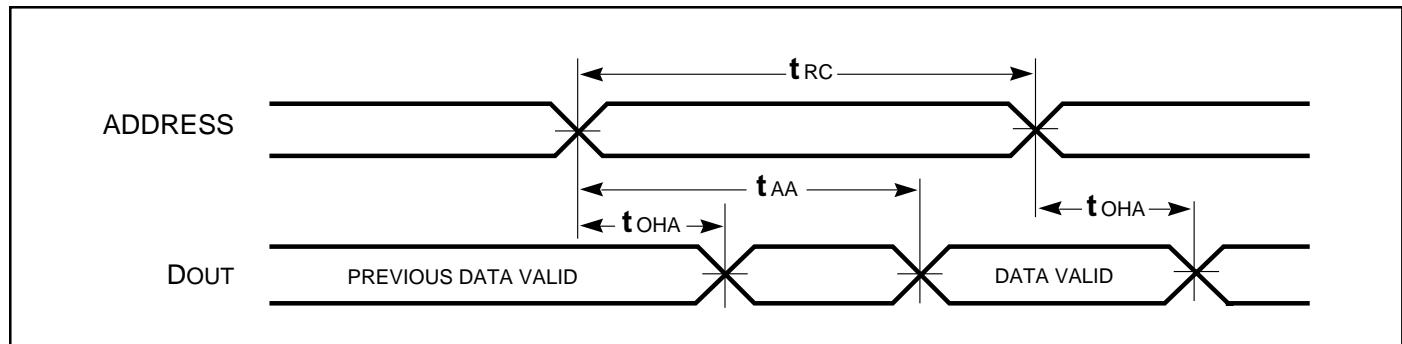
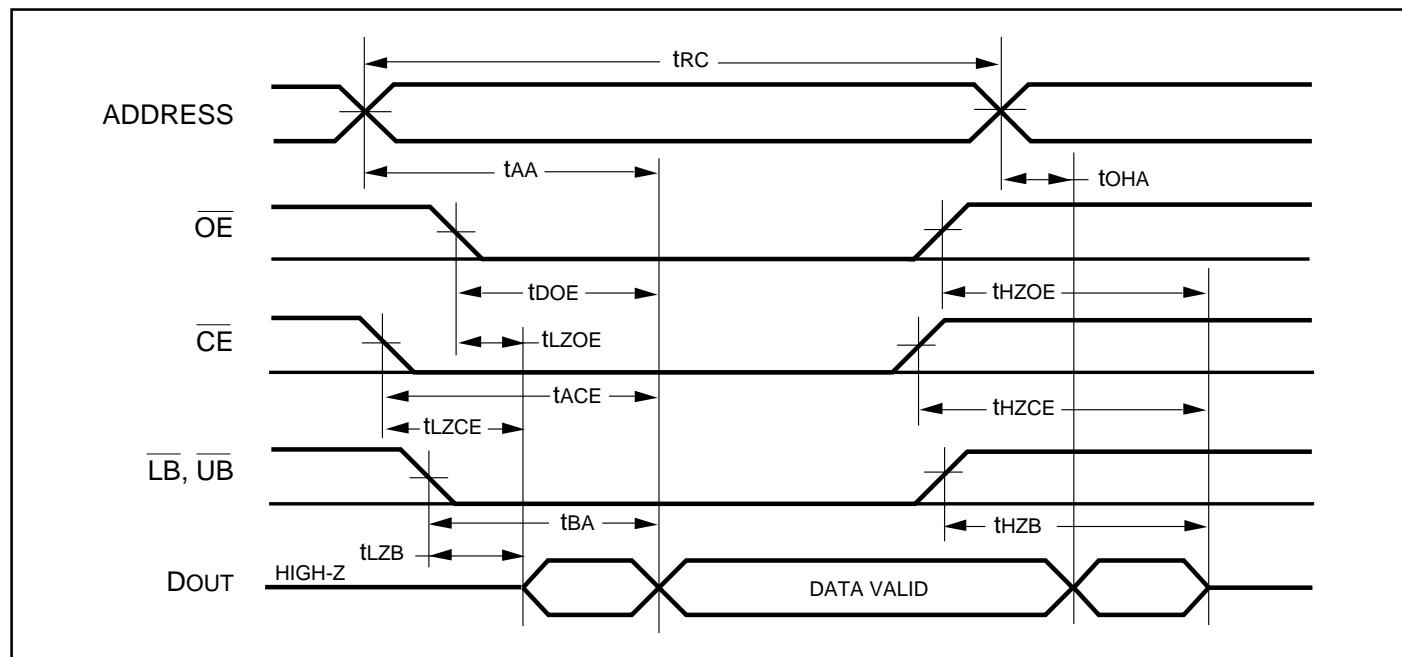


Figure 2

AC WAVEFORMS

READ CYCLE NO. 1^(1,2) (Address Controlled) ($\overline{CE} = \overline{OE} = V_{IL}$, \overline{UB} or $\overline{LB} = V_{IL}$)READ CYCLE NO. 2^(1,3)

Notes:

1. \overline{WE} is HIGH for a Read Cycle.
2. The device is continuously selected. \overline{OE} , \overline{CE} , \overline{UB} , or $\overline{LB} = V_{IL}$.
3. Address is valid prior to or coincident with \overline{CE} LOW transition.

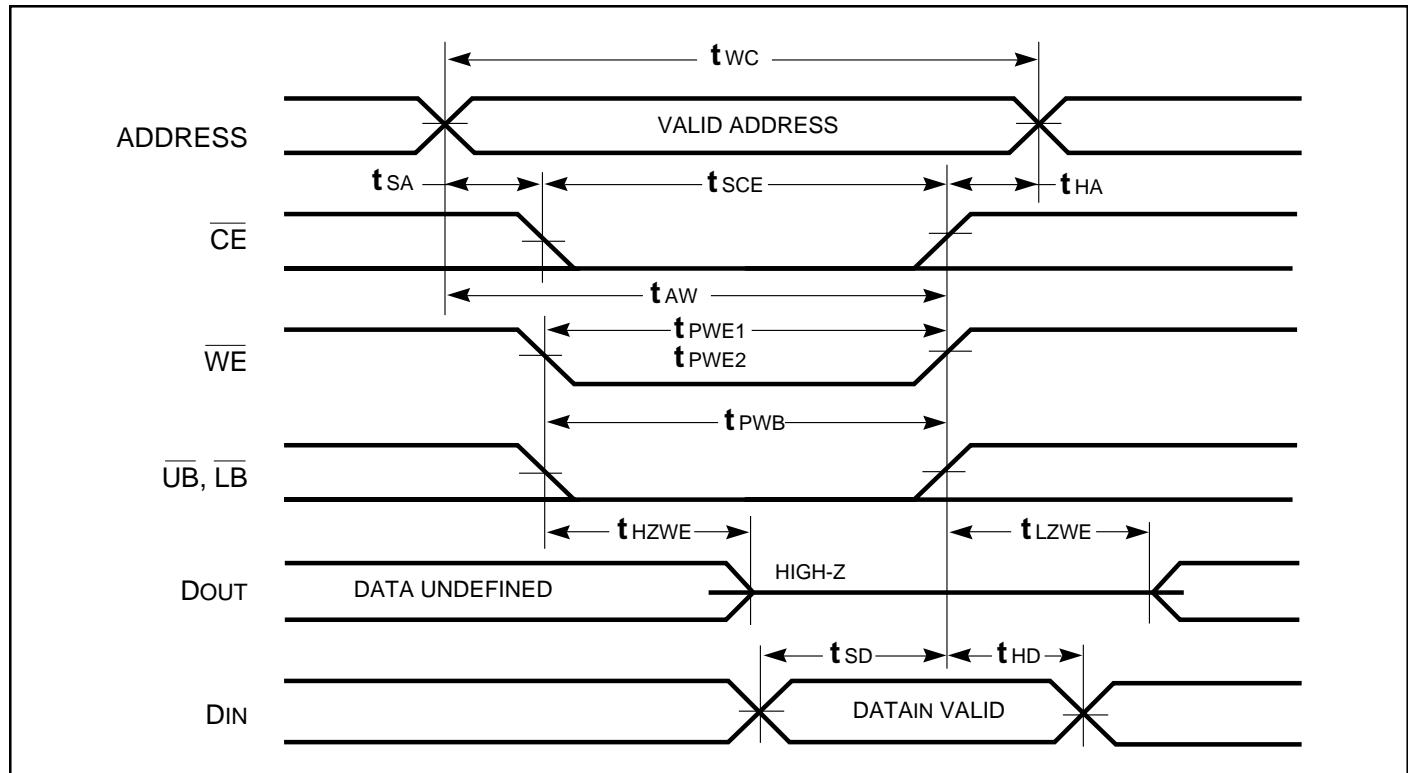
WRITE CYCLE SWITCHING CHARACTERISTICS^(1,3) (Over Operating Range)

Symbol	Parameter	-8		-10		-12		-15		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t _{WC}	Write Cycle Time	8	—	10	—	12	—	15	—	ns
t _{SCE}	\overline{CE} to Write End	7	—	8	—	9	—	10	—	ns
t _{AW}	Address Setup Time to Write End	7	—	8	—	9	—	10	—	ns
t _{HA}	Address Hold from Write End	0	—	0	—	0	—	0	—	ns
t _{SA}	Address Setup Time	0	—	0	—	0	—	0	—	ns
t _{PWB}	\overline{LB} , \overline{UB} Valid to End of Write	7	—	8	—	9	—	10	—	ns
t _{PWE}	\overline{WE} Pulse Width	7	—	8	—	9	—	10	—	ns
t _{SD}	Data Setup to Write End	4.5	—	5	—	6	—	7	—	ns
t _{HD}	Data Hold from Write End	0	—	0	—	0	—	0	—	ns
t _{HZWE⁽²⁾}	\overline{WE} LOW to High-Z Output	—	4	—	5	—	6	—	7	ns
t _{LZWE⁽²⁾}	\overline{WE} HIGH to Low-Z Output	3	—	3	—	3	—	3	—	ns

Notes:

1. Test conditions assume signal transition times of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V and output loading specified in Figure 1a.
2. Tested with the load in Figure 1b. Transition is measured ± 500 mV from steady-state voltage. Not 100% tested.
3. The internal write time is defined by the overlap of \overline{CE} LOW and \overline{UB} or \overline{LB} , and \overline{WE} LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the write.

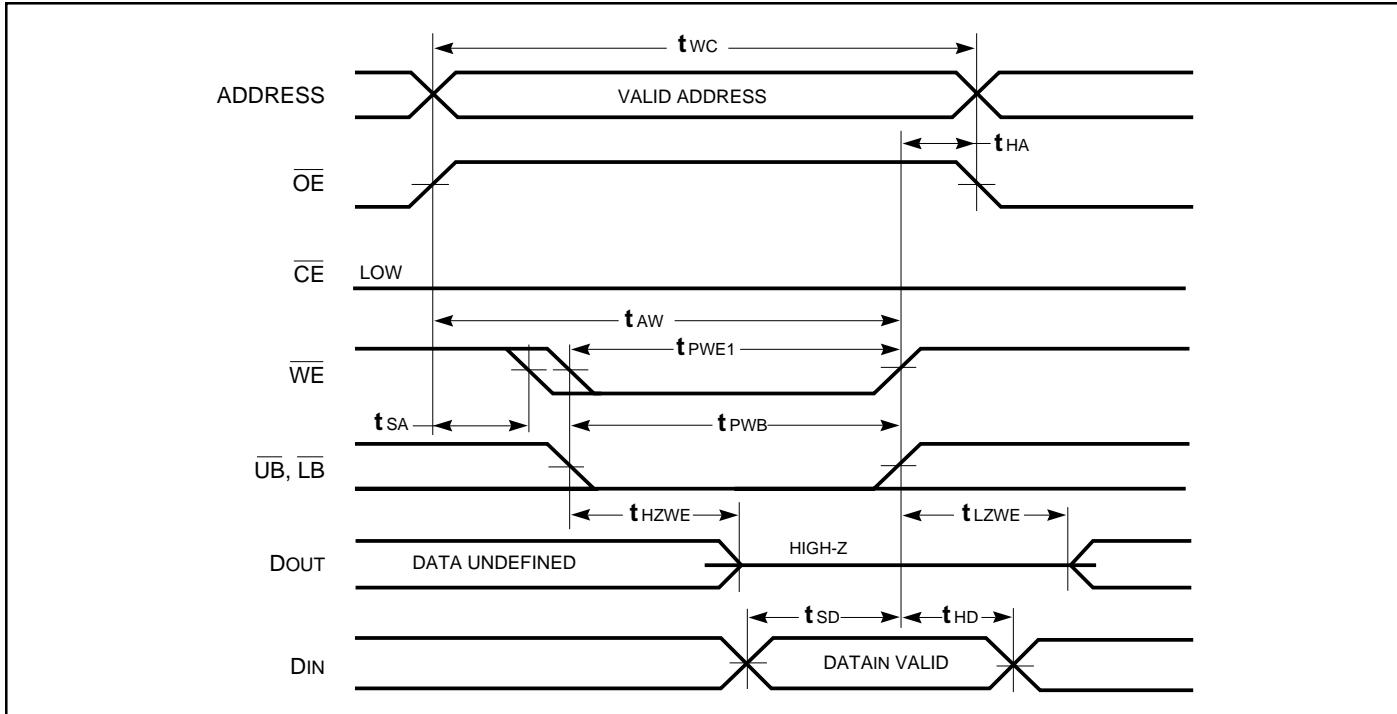
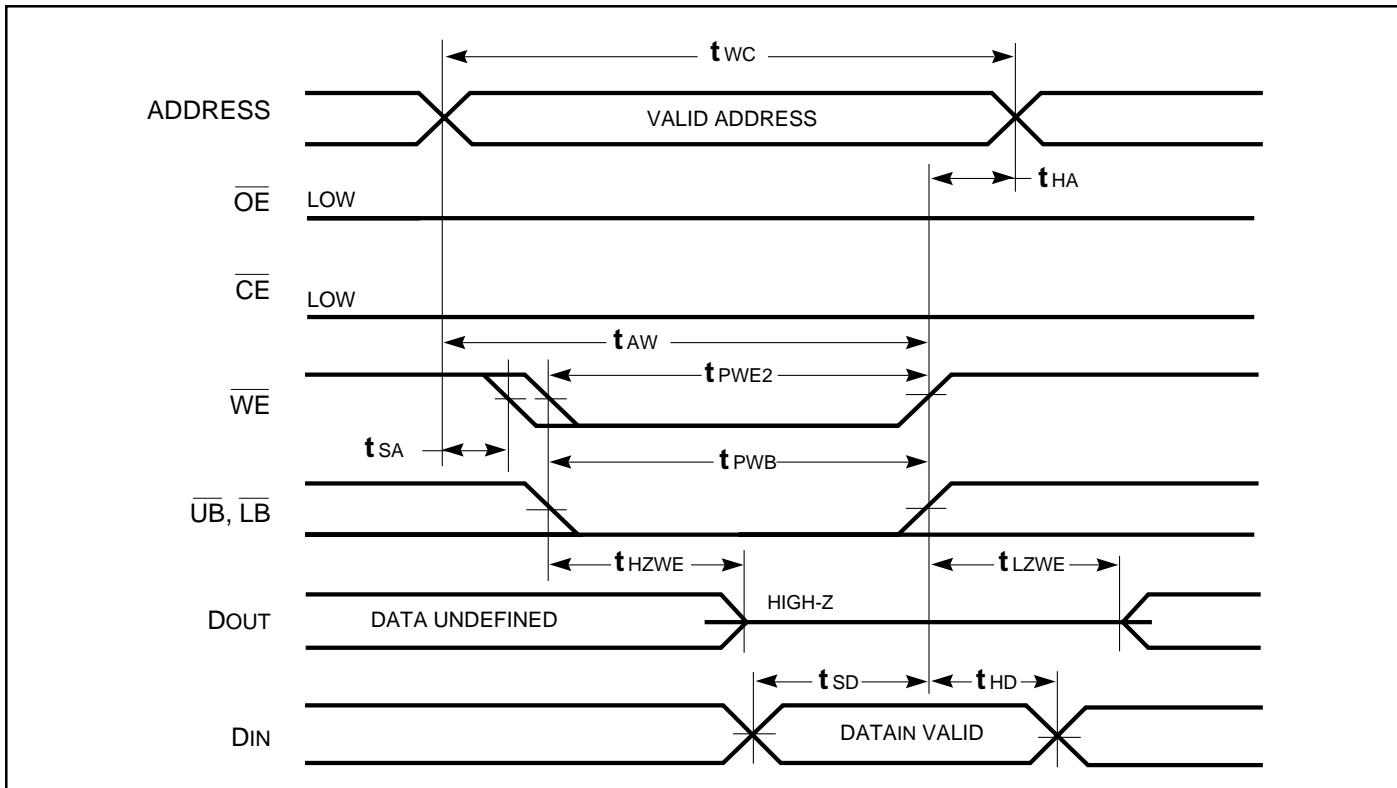
AC WAVEFORMS

WRITE CYCLE NO. 1 (\overline{CE} Controlled, \overline{OE} is HIGH or LOW)⁽¹⁾

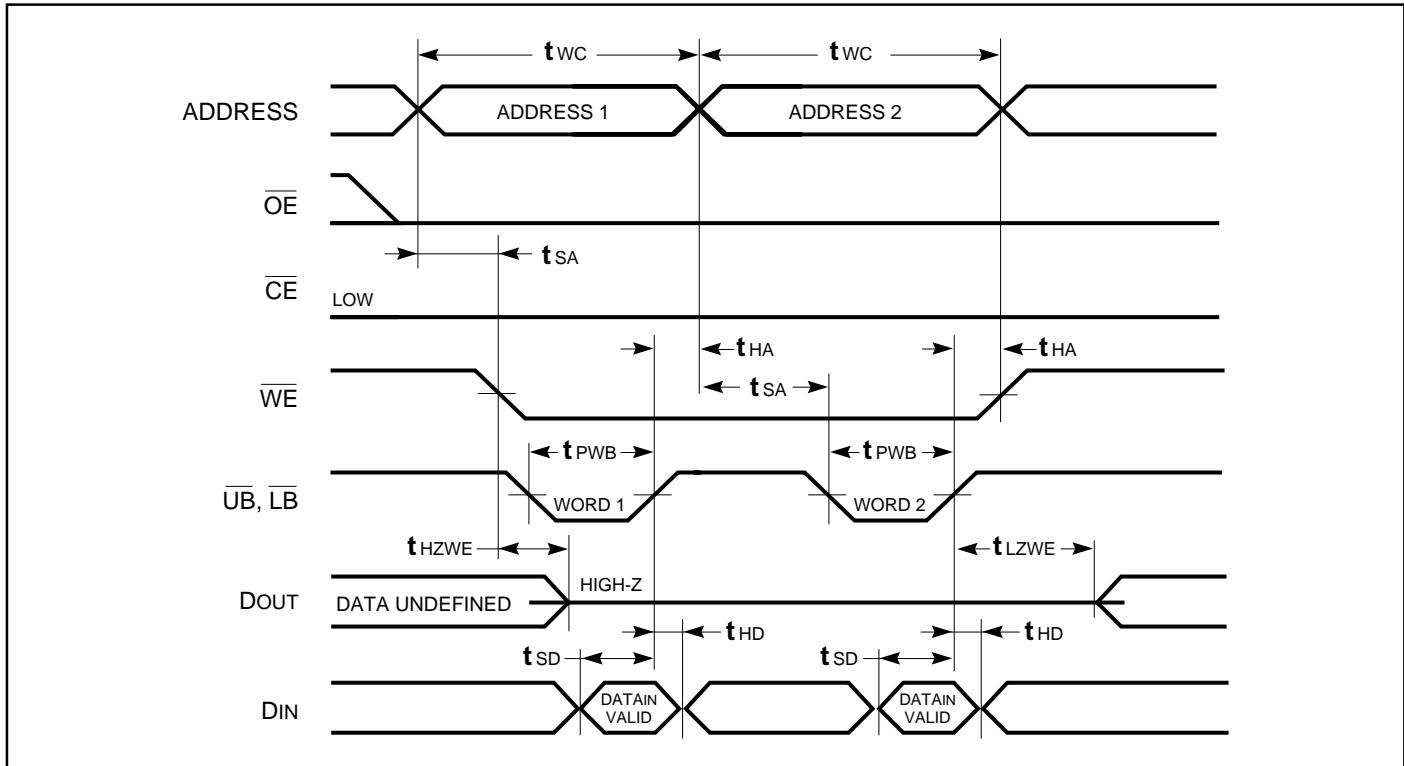
Notes:

1. WRITE is an internally generated signal asserted during an overlap of the LOW states on the \overline{CE} and \overline{WE} inputs and at least one of the \overline{LB} and \overline{UB} inputs being in the LOW state.
2. $\text{WRITE} = (\overline{CE}) [(\overline{LB}) = (\overline{UB})] (\overline{WE})$.

AC WAVEFORMS

WRITE CYCLE NO. 2 (\overline{WE} Controlled. \overline{OE} is HIGH During Write Cycle) ^(1,2)WRITE CYCLE NO. 3 (\overline{WE} Controlled. \overline{OE} is LOW During Write Cycle) ⁽¹⁾

AC WAVEFORMS

WRITE CYCLE NO. 4 (\overline{LB} , \overline{UB} Controlled, Back-to-Back Write) ^(1,3)

Notes:

1. The internal Write time is defined by the overlap of $\overline{CE} = \text{LOW}$, \overline{UB} and/or $\overline{LB} = \text{LOW}$, and $\overline{WE} = \text{LOW}$. All signals must be in valid states to initiate a Write, but any can be deasserted to terminate the Write. The t_{SA} , t_{HA} , t_{SD} , and t_{HD} timing is referenced to the rising or falling edge of the signal that terminates the Write.
2. Tested with $OE = \text{HIGH}$ for a minimum of 4 ns before $\overline{WE} = \text{LOW}$ to place the I/O in a HIGH-Z state.
3. \overline{WE} may be held LOW across many address cycles and the \overline{LB} , \overline{UB} pins can be used to control the Write function.

ORDERING INFORMATION

Commercial Range: 0°C to +70°C

Speed (ns)	Order Part No.	Package
8	IS61LV25616-8T	400mil TSOP-2
	IS61LV25616-8K	400mil SOJ
	IS61LV25616-8B	6*8mm TF-BGA
10	IS61LV25616-10T	400mil TSOP-2
	IS61LV25616-10K	400mil SOJ
	IS61LV25616-10B	6*8mm TF-BGA
12	IS61LV25616-12T	400mil TSOP-2
	IS61LV25616-12K	400mil SOJ
	IS61LV25616-12B	6*8mm TF-BGA
15	IS61LV25616-15T	400mil TSOP-2
	IS61LV25616-15K	400mil SOJ
	IS61LV25616-15B	6*8mm TF-BGA

ORDERING INFORMATION

Industrial Range: -40°C to +85°C

Speed (ns)	Order Part No.	Package
8	IS61LV25616-8TI	400mil TSOP-2
	IS61LV25616-8KI	400mil SOJ
	IS61LV25616-8BI	6*8mm TF-BGA
10	IS61LV25616-10TI	400mil TSOP-2
	IS61LV25616-10KI	400mil SOJ
	IS61LV25616-10BI	6*8mm TF-BGA
12	IS61LV25616-12TI	400mil TSOP-2
	IS61LV25616-12KI	400mil SOJ
	IS61LV25616-12BI	6*8mm TF-BGA
15	IS61LV25616-15TI	400mil TSOP-2
	IS61LV25616-15KI	400mil SOJ
	IS61LV25616-15BI	6*8mm TF-BGA

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